

Digital transistors (built-in resistors)

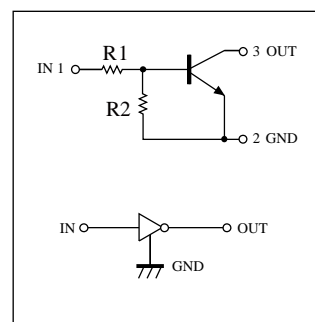
• Features

- 1) Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see the equivalent circuit).
- 2) The bias resistors consist of thin-film resistors with complete isolation to allow negative biasing of the input. They also have the advantage of almost completely eliminating parasitic effects.
- 3) Only the on/off conditions need to be set for operation, making device design easy.



• Device Marking and Ordering Information

Device	Marking	Shipping
DTC505T1G	8M	3000/Tape&Reel
DTC505T3G	8M	10000/Tape&Reel



• Absolute maximum ratings ($T_A = 25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Supply voltage	V_{CC}	50	V
Input voltage	V_{IN}	-5~+12	V
Output current	I_O	100	mA
	$I_{C(Max)}$	100	
Power dissipation	P_d	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55~+150	$^\circ\text{C}$

• Electrical characteristics ($T_A = 25^\circ\text{C}$)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Input voltage	$V_{I(off)}$	-	-	0.5	V	$V_{CC} = 5V, I_O = 100\mu A$
	$V_{I(on)}$	1.1	-	-		$V_O = 0.3V, I_O = 5mA$
Output voltage	$V_{O(on)}$	-	0.1	0.3	V	$I_O/I_I = 5mA/0.25mA$
Input current	I_I	-	-	3.6	mA	$V_I = 5V$
Output current	$I_{O(off)}$	-	-	0.5	μA	$V_{CC} = 50V, V_I = 0V$
DC current gain	G_I	80	-	-	-	$V_O = 5V, I_O = 10mA$
Input resistance	R_1	1.54	2.2	2.86	k Ω	-
Resistance ratio	R_2/R_1	17	21	26	-	-
Transition frequency	f_T	-	250	-	MHz	$V_{CE} = 10V, I_E = -5mA, f = 100MHz$ *

* Transition frequency of the device

• **Electrical characteristic curves**

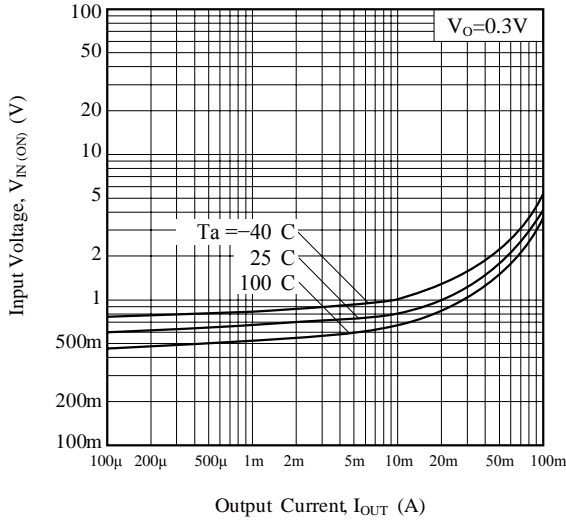


Fig.1 Input Voltage vs. Output Current (ON Characteristics)

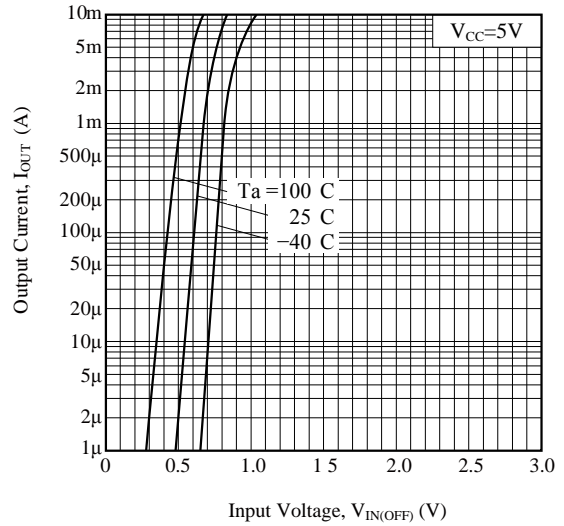


Fig.2 Output Current vs. Input Voltage (OFF Characteristics)

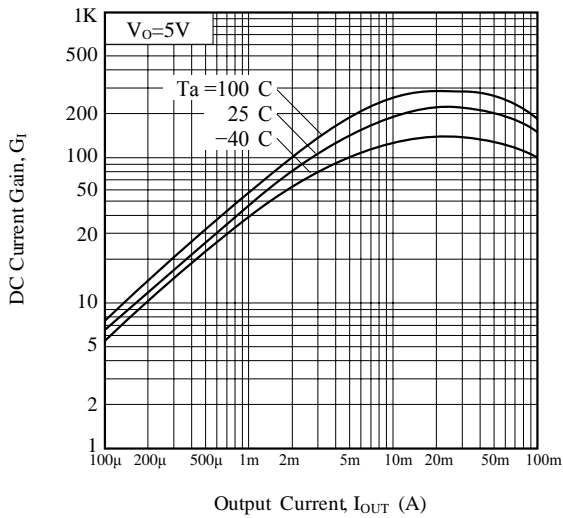


Fig.3 DC Current Gain vs. Output Current

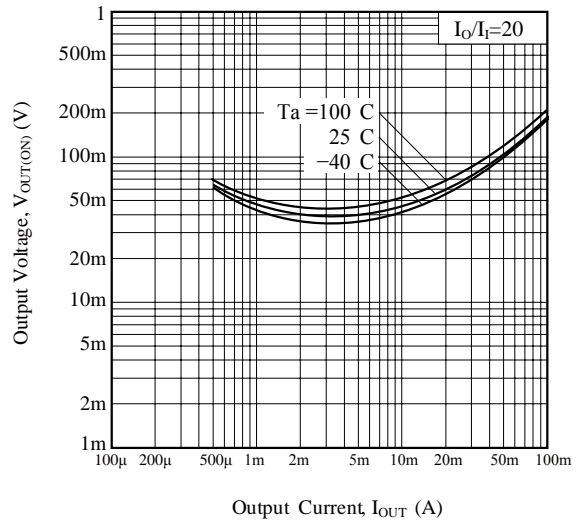
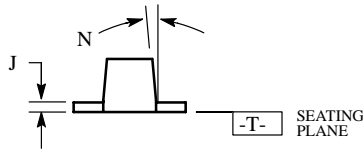
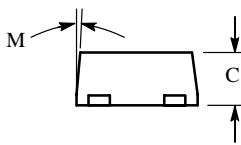
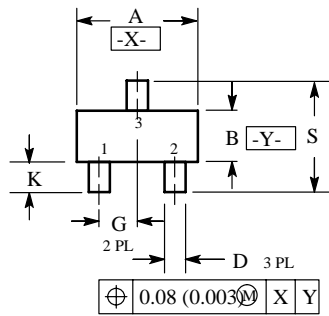


Fig.4 Output Voltage vs. Output Current

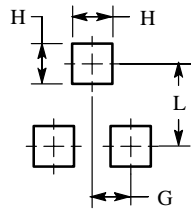
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NOTES:

- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
- 2 CONTROLLING DIMENSION: MILLIMETERS
- 3 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4 463C-01 OBSOLETE, NEW STANDARD 463C-02

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.60	1.70	0.059	0.063	0.067
B	0.75	0.85	0.95	0.030	0.034	0.040
C	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G	0.50BSC			0.020BSC		
H	0.53RBF			0.021RBF		
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L	1.10RBF			0.043RBF		
M	-	-	10°	-	-	10°
N	-	-	10°	-	-	10°
S	1.50	1.60	1.70	0.059	0.063	0.067



RECOMMENDED PATTERN OF SOLDER PADS